

E1.S CONNECTOR FORM FACTOR

JEDEC SOLID STATE  
PRODUCT OUTLINE  
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AND REFLECTS A PRODUCT WITH ANTICIPATED USAGE IN THE ELECTRONICS INDUSTRY;  
CHANGES ARE LIKELY TO OCCUR.

TITLE ENCLOSURE FORM  
FACTOR FOR AUTOMOTIVE SSD  
CONNECTOR, BOARD MOUNT

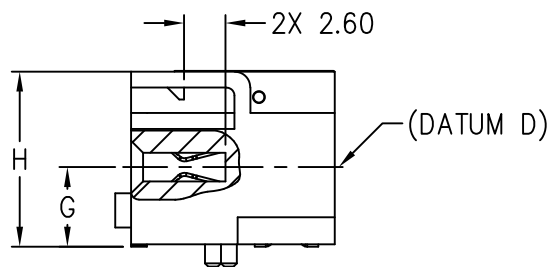
PACKAGE DESIGNATOR  
PBCX-K4\_...

NUMBER  
SO-030

ISSUE  
A

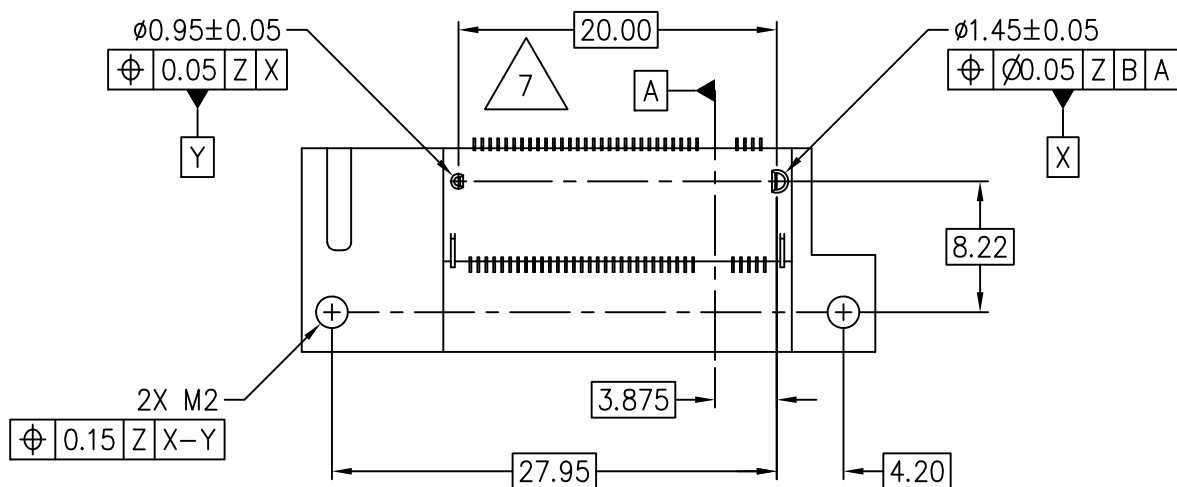
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FEB 2022

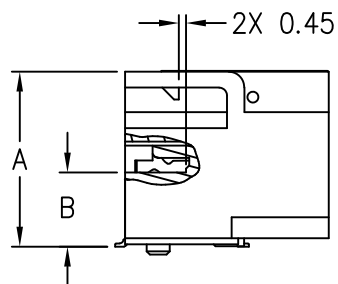
SHEET  
1 OF 6



SECTION A-A  
E1.S CONNECTOR SIDE VIEW

VARIATIONS IN SFF-TA-1002 RIGHT ANGLE CONNECTOR HEIGHT			
SYMBOL	HEIGHT 1	HEIGHT 2	NOTES
G	(3.05)	(4.05)	6
H	9.25 MAX	10.25 MAX	
NOTES	1, 2, 3, 4, 6	1, 2, 3, 4, 6	
REF	14-211	14-211	
ISSUE	A	A	





SECTION B-B  
M.2 M KEY CONNECTOR SIDE VIEW

VARIATIONS IN PCI EXPRESS M.2 SPEC CONNECTOR HEIGHT						
SYMBOL	SEATING HEIGHT 1	SEATING HEIGHT 2	SEATING HEIGHT 3	SEATING HEIGHT 4	SEATING HEIGHT 5	NOTES
A	6.90 MAX	7.10 MAX	7.40 MAX	7.85 MAX	8.85 MAX	
B	(0.41)	(0.61)	(0.89)	(1.54)	(2.54)	7
NOTES	1, 2, 3, 4, 7					
REF	14-211					
ISSUE	A					

NOTES:

1. DIMENSIONING AND TOLERANCING PER ASME Y14.5–2009.
2. TOLERANCES ON ALL DIMENSIONS  $\pm 0.15$  UNLESS OTHERWISE SPECIFIED.
3. ALL DIMENSIONS ARE MM.
4. METAL SURFACE SHALL BE FREE OF BURRS.
5. THIS DOCUMENT DEFINES CONNECTOR ENCLOSURE VOLUMETRIC FOR TWO VARIATION OF SSD INTERFACE: E1.S AND M.2 M KEY SSD

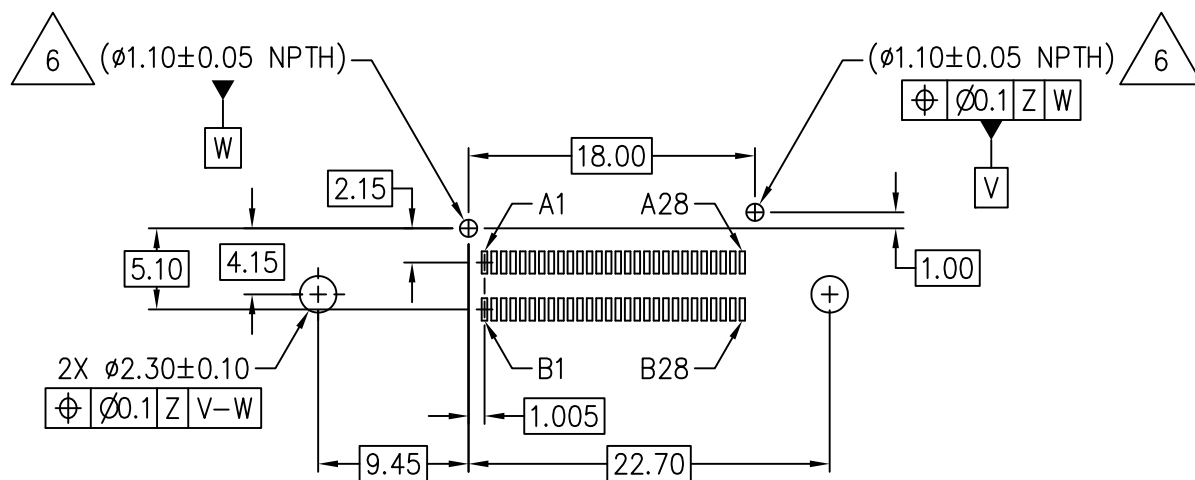


THE E1.S CONNECTOR DIMENSIONS AND DATUM REFER TO SNIA SFF–TA–1002 SPECIFICATION REV 1.3.



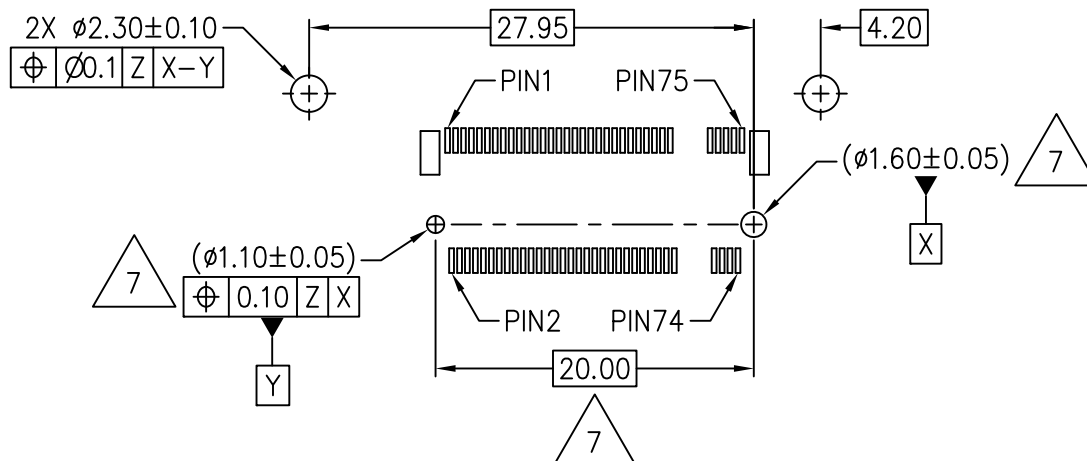
THE M.2 CONNECTOR DIMENSIONS AND DATUM REFER TO PCI EXPRESS M.2 SPECIFICATION R4.0 V1.0.

8. FOR E1.S CONNECTOR PCB TERMINAL PATTERN REFER TO BELOW.  
REFER TO SNIA SFF–TA–1002, SPECIFICATION FOR PROTOCOL AGNOSTIC MULTI-LANE HIGH SPEED CONNECTOR DOCUMENT FOR TERMINAL PATTERN DIMENSIONS.



E1.S PCB FOOTPRINT  
DATUM Z: PCB SOLDER SURFACE

9. FOR M.2 CONNECTOR PCB TERMINAL PATTERN REFER TO BELOW.  
REFER TO PCI EXPRESS M.2 SPECIFICATION DOCUMENT FOR TERMINAL PATTERN DIMENSIONS  
AND MODULE MOUNTING SCREW GROUNDING INFORMATION.



M.2 M KEY PCB FOOTPRINT  
DATUM Z: PCB SOLDER SURFACE

10. VARIOUS COMPANIES HAVE ISSUED PATENTS AND RELATED PATENT APPLICATIONS THAT MAY APPLY TO THIS REGISTRATION. IF THE CURRENT ISSUE PATENTS OR LATER PATENTS RESULTING FROM RELATED APPLICATION DO APPLY, THESE COMPANIES INTEND TO COMPLY WITH THE JEDEC PATENT POLICY AND LICENSE UNDER REASONABLE TERMS AND CONDITIONS THAT ARE DEMONSTRABLY FREE OF ANY UNFAIR DISCRIMINATION. REFERENCED PATENTS ARE AS FOLLOWS.

AMPHENOL	CHINA PATENT ZL202021981365.4 US17/402,280 & CN202010952023.8
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STP (3D) FILE RECORD  
3D FILE NAMES MAY EXCEED LENGTH REQUIREMENTS FOR SOME SOFTWARE TOOLS.

STP FILE NAME	DATE	ITEM NUMBER
SO-030A_PBXC-K4_D6p972266-MR36p05x13p0Z9p25-HS_ES.1	FEB-2022	14-211
SO-030A_PBXC-K4_D6p972266-MR36p05x13p0Z10p25-HS_ES.1	FEB-2022	14-211
SO-030A_PBXC-K4_D9p23084-MR36p05x13p0Z6p9-HS_M.2	FEB-2022	14-211
SO-030A_PBXC-K4_D9p23084-MR36p05x13p0Z7p1-HS_M.2	FEB-2022	14-211
SO-030A_PBXC-K4_D9p23084-MR36p05x13p0Z7p4-HS_M.2	FEB-2022	14-211
SO-030A_PBXC-K4_D9p23084-MR36p05x13p076p85-HS_M.2	FEB-2022	14-211
SO-030A_PBXC-K4_D9p23084-MR36p05x13p0Z8p85-HS_M.2	FEB-2022	14-211

TASK GROUP CONTRIBUTORS

AMPHENOL



# CHANGE RECORD

IF THE CHANGE INVOLVES ANY WORDS ADDED OR DELETED (EXCLUDING DELETION OF ACCIDENTALLY REPEATED WORDS), THE CHANGE IS TO BE INCLUDED BELOW. PUNCTUATION CHANGES MAY OR MAY NOT BE INCLUDED.

INITIAL ISSUE: A	DATE: FEBRUARY 2022	ITEM NUMBER: 14-211
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CHANGE RECORD HISTORY:
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INITIAL ISSUE:	DATE:	ITEM NUMBER: -
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LOCATION:	CHANGED FROM:	CHANGED TO: